

Technical specification/

Technische Daten:

Dielectric withstanding voltage/ <i>Spannungsfestigkeit:</i>	1000 V, 50 Hz 1 min.
Current rating/ <i>Strombelastbarkeit:</i>	Signal contact 7,5 A (UL), <i>Signalkontakt</i> 5 A (CSA,VDE) High power press-fit contact 30 A <i>Hochstrom Press-Fit Kontakt</i>
Insulation resistance/ <i>Isolationswiderstand:</i>	≥ 5 GΩ
Temperature range/ <i>Temperaturbereich:</i>	- 55 °C ... + 125 °C
Mating cycles/ <i>Steckzyklen:</i>	Quality class 3 = 50 <i>Gütestufe 3</i>

Materials/

Werkstoffe:

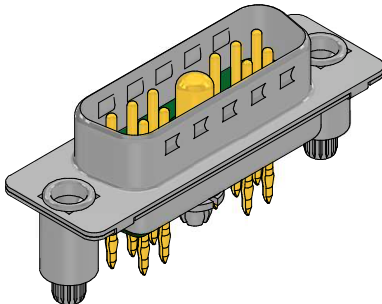
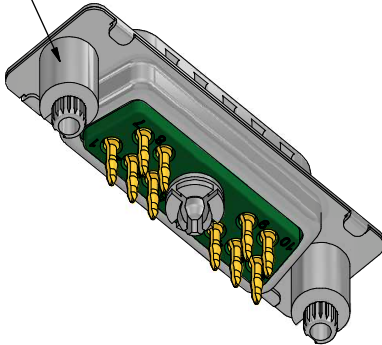
Signal contact/ <i>Signalkontakt:</i>	Cu alloy, Au over Ni
High power press-fit contact/ <i>Hochstrom Press-Fit Kontakt:</i>	Cu alloy, mating side/ <i>Steckseite</i> <i>Au over Ni</i> <i>press-fit area / Press-Fit Bereich</i> Sn over Ni
Insulator/ <i>Isolierkörper:</i>	PBT GF UL 94 V-0, green/ <i>grün</i>
Shell/ <i>Gehäuse:</i>	Steel, Sn over Ni
Threaded push in pin/ <i>Gewinde-Einpressbolzen:</i>	Cu alloy, Sn

Installation specification/

Montagedaten:

Recommended torque value for thread/ <i>Empfohlenes Drehmoment für Gewinde:</i>	max. 6 in.LB/ <i>max. 67 Ncm</i>
PCB thickness/ <i>Leiterplattenstärke:</i>	min. 2,0 mm

Threaded push in pin/
Gewinde-Einpressbolzen

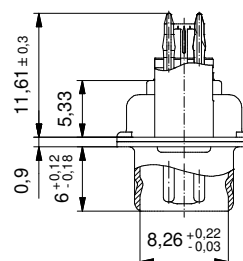
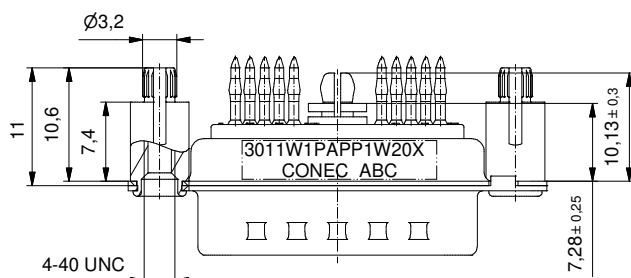
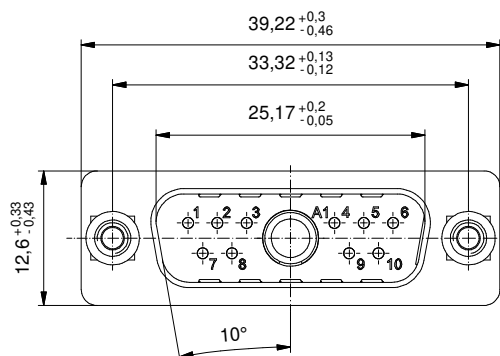
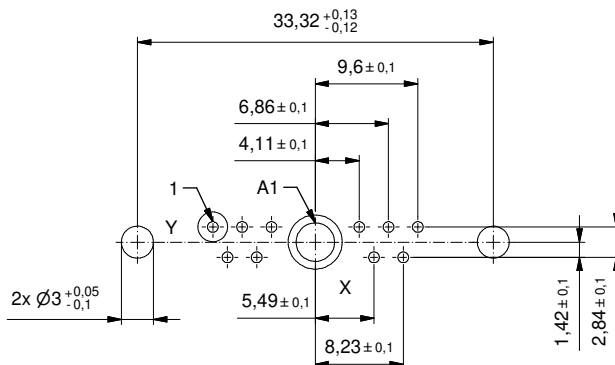


Part no. / Part marked/ Art.-Nr. / Bedruckung:		Contact plating/ Kontakt Veredelung:			
3011W1PAPP1W20X	Signal contact/ Signalkontakt:	gold flash over nickel Gold über Nickel			
	High power press-fit contact 30 A/ Hochstrom Press-Fit Kontakt 30 A:	plating, mating side: Veredelung, Steckseite: plating, press-fit area: Veredelung, Press-Fit Bereich:	30 µin hard gold over min. 50 µin nickel 30 µin Gold über min. 50 µin Nickel tin over nickel Zinn über Nickel		
			dim. in mm	D-SUB Combination Male 11W1P press-fit with threaded push in pin D-SUB Combination Stiftleiste 11W1P Press-Fit mit Gewinde-Einpressbolzen	
general tolerance/ Allgemeintoleranz:	0 ± 0,50 mm 0,0 ± 0,25 mm 0,00 ± 0,10 mm ° ± 5°		Date/Datum		Name
		drawn/ gez.	03.12.2021		Henneboel
		appd./ gepr.	03.12.2021		Lehmenkühle
Index: a Original	scale/Maßstab: 2:1			dwg no / Z.-nr.: 13K1A6314	DIN- A3
RoHS compliant/konform					1 / 2

Y (5 : 1)

10x Finished hole/
Endloch: $\varnothing 1^{+0,09}_{-0,06}$ Copper thickness/
Cu Schichtdicke:
25 μm (1000 μin) min.Tin thickness/
Sn Schichtdicke:
15 μm (600 μin) max.10x Drilled hole/
Bohrloch $\varnothing 1,15 \pm 0,025$

X (5 : 1)

Copper thickness/
Cu Schichtdicke:
25 μm (1000 μin) min.Tin thickness/
Sn Schichtdicke:
15 μm (600 μin) max.Finished hole after reflow/
Endloch: $\varnothing 3,4$ min. - $\varnothing 3,11$ max.PCB hole drillings
(PCB top side)/
Leiterplattenbohrbild
(Leiterplatten Oberseite)

			dim. in mm	D-SUB Combination Male 11W1P press-fit with threaded push in pin	
		drawn/	Date/Datum	D-SUB Combination Stiftleiste 11W1P Press-Fit mit Gewinde-Einpressbolzen	
		ges.	03.12.2021		
		appd./	03.12.2021		
		gepr.	Lehmenkühle		
Index:	a Original	scale/Maßstab:		dwg no / Z.-nr.:	13K1A6314
Status:	InBearbeitung	2:1			DIN-A3
RoHS compliant/konform					2 / 2